



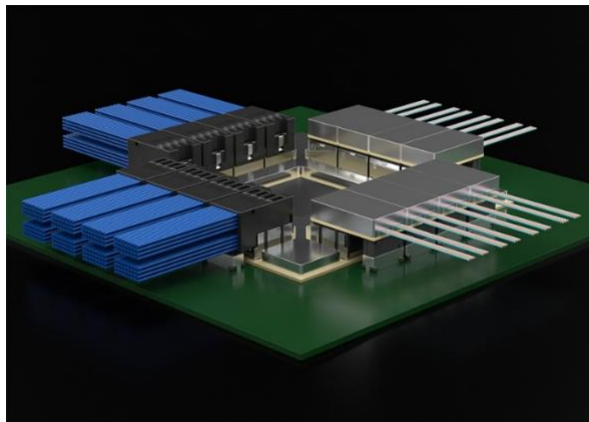
Samtec Showcases High-Density Interconnect Technology at AI Infra Summit

Samtec high-density optical and copper interconnects will be showcased in booth 304.

August 31, 2026 [New Albany, IN]-- Samtec, Inc., the service leader in the connector industry, will be demonstrating next-generation, high-performance optical and copper interconnect solutions at the upcoming [AI Infra Summit](#), the premier full-stack AI Infrastructure conference for enterprise practitioners, data scientists, ML engineers, platform engineers, and technical leads at hyperscalers and large enterprises.

Held in Santa Clara, CA (September 15-17, 2026) at the Santa Clara Convention Center, AI Infra Summit includes a technical conference as well as an exhibition. The 2026 event anticipates 8,000 attendees, 400 speakers, and 8 stages. The content for the event is divided into tracks, including Compute, Data Movement, Physical AI, Data & Models, as well as AI Data Center.

Samtec Innovative Interconnect in Booth 304



Samtec will be demonstrating high-speed, high-density optical and copper interconnects that are well suited for use in datacenters, AI/high-performance computing, and telecom/edge applications. Demonstrations will include [PCIe 5.0 over Firefly optical cable assemblies](#), the new [Si-FLY® HD](#) 224 Gbps PAM4 co-packaged and near-chip systems, as well as Si-Fly HD prototypes for 448Gbps PAM4/PAM6.

Samtec's Si-Fly HD CPX system is an electrically pluggable co-packaged copper and optics solution, achievable on a 95 mm x 95 mm or smaller substrate using Samtec's SFCM connector. The SFCM mounts directly to the package substrate and is pluggable with Samtec's SFCC cable assembly or is interoperable with industry-standard optical cable assemblies. Co-packaged connectivity eliminates insertion losses in the BGA breakout and PCB and enables a complete passive DAC 224G channel that is extreme performance as well as low cost.

Technical Talks on Interconnect Technology

Matt Burns, Global Director of Technical Marketing at Samtec will be presenting two technical talks at AI Infra Summit 2026:

- 224/448 Gbps Copper and Optics: Can I Have Both? on 15 September from 3:50 to 4:10 in the Data Movement Track
- 400G AI Scale Up/Scale Out Implementation - A Path to Reality 16 September from 11:00-11:15 in Expo Theater 2.



More Information

- Samtec's optical products, visit www.samtec.com/optics
- Samtec's Si-Fly HD co-packaged and near-chip systems visit: www.samtec.com/si-fly-hd
- Samtec's Datacom Industry page, visit [Datacom Connectors and Product Applications](#)
- White Paper, "[Achieving 224 Gbps PAM4: New Interconnect Methods to Ensure Signal Integrity](#)"

About Samtec

Founded in 1976, Samtec is a privately held, \$1 Billion dollar global manufacturer of a broad line of electronic interconnect solutions, including High-Speed Board-to-Board, High-Speed Cables, Mid-Board and Panel Optics, Precision RF, Flexible Stacking, and Micro/Rugged components and cables. Samtec Technology Centers are dedicated to developing and advancing technologies, strategies, and products to optimize both the performance and cost of a system from the bare die to an interface 100 meters away, and all interconnect points in between. With 40+ international locations and products sold in more than 125 different countries, Samtec's global presence enables its unmatched customer service. For more information, please visit: www.samtec.com.

Our press team enjoys working with journalists around the world to share compelling and innovative stories. If you are a member of the media/press and would like to talk, please send an email to mediaroom@samtec.com.